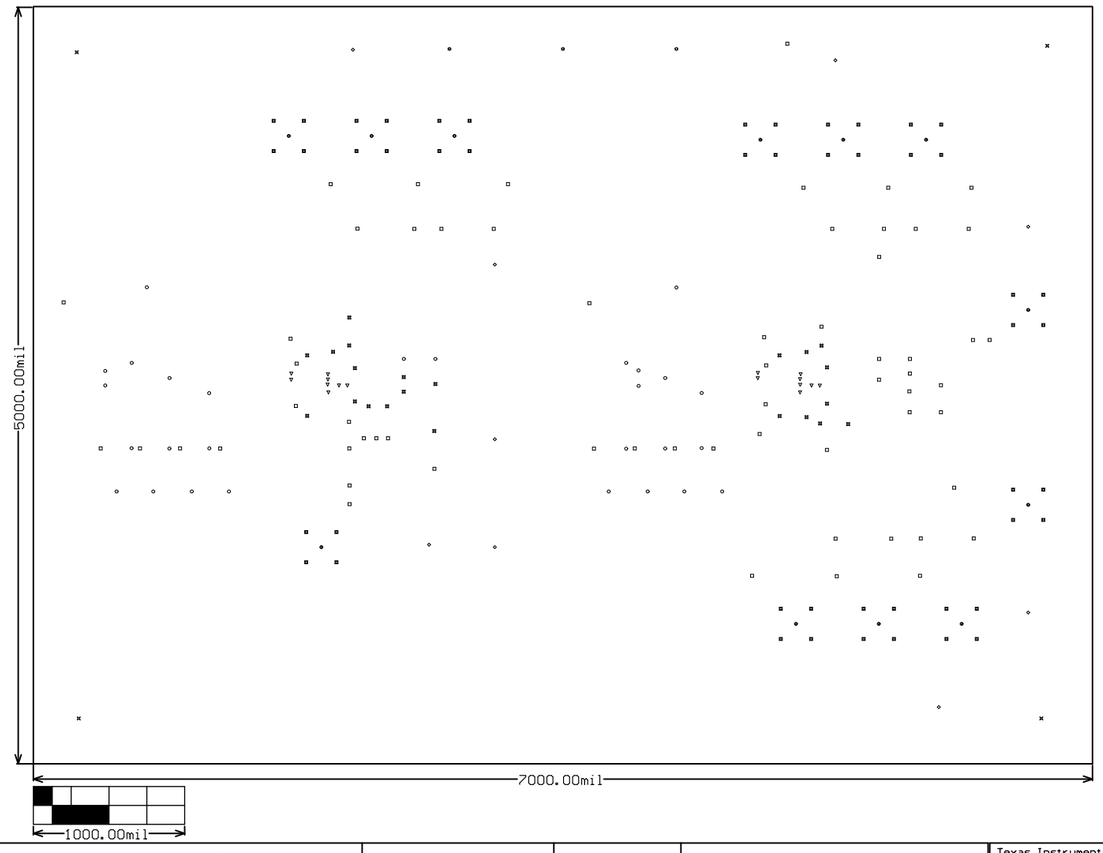
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 2		10.00mil	4.2	
5	Int 2 V-	Copper	1.42mil		
6	Dielectric1	FR-4	36.00mil	4.8	
7	Int 3 V+	Copper	1.42mil		
8	Dielectric 3		10.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

Symbol	Quantity	Finished Hole Size	Plating	Hole Type	Drill Layer Pair	Hole Tolerance
	116	4,00mil (0,100mm)	PTH	Round	Top Layer - Bottom Layer	
	22	10,00mil (0,254mm)	PTH	Round	Top Layer - Bottom Layer	
○	28	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
□	61	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
◇	9	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
◎	12	59.06mil (1.500mm)	PTH	Round	Top Layer - Bottom Layer	
▣	48	62.99mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⌑	4	125.00mil (3,175mm)	PTH	Round	Top Layer - Bottom Layer	
☼	3	214.57mil (5.450mm)	PTH	Round	Top Layer - Bottom Layer	
	203 Total					



DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: OPA3S328EVM
DESIGNED FOR: Public Release
FILE NAME: AMPS084.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AMPS084	REV: A	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 9/7/2022 11:56:52 AM		TEXAS INSTRUMENTS

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ENGINEER:	LAYOUT BY:
L Chioye	L Chioye
SCALE: 1.00	ALTIUM DESIGNER VERSION: 18.1.9.240